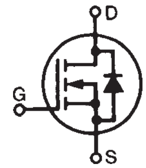
IXYS

TrenchMV™ Power MOSFET

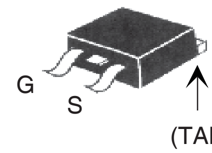
IXTA130N10T
IXTP130N10T

V_{DSS} = 100V
I_{D25} = 130A
$R_{DS(on)}$ ≤ 9.1mΩ

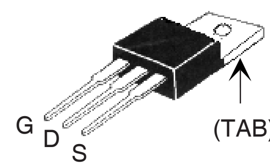
N-Channel Enhancement Mode
Avalanche Rated



TO-263 (IXTA)



TO-220 (IXTP)



G = Gate D = Drain
S = Source TAB = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 175°C	100	V
V_{DGR}	T_J = 25°C to 175°C, R_{GS} = 1MΩ	100	V
V_{GSM}	Transient	± 30	V
I_{D25}	T_C = 25°C	130	A
I_{LRMS}	Lead Current Limit, RMS	75	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}	350	A
I_A	T_C = 25°C	65	A
E_{AS}	T_C = 25°C	500	mJ
P_D	T_C = 25°C	360	W
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +175	°C
T_L	1.6mm (0.062 in.) from case for 10s	300	°C
T_{SOLD}	Plastic body for 10 seconds	260	°C
M_d	Mounting torque (TO-220)	1.13 / 10	Nm/lb.in.
Weight	TO-220	3.0	g
	TO-263	2.5	g

Symbol	Test Conditions		Characteristic Values			
(T_J = 25°C unless otherwise specified)			Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 250µA		100			V
$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250µA		2.5		4.5	V
I_{GSS}	V_{GS} = ± 20V, V_{DS} = 0V				± 200	nA
I_{DSS}	V_{DS} = V_{DSS}				5	µA
	V_{GS} = 0V	T_J = 150°C			250	µA
$R_{DS(on)}$	V_{GS} = 10V, I_D = 25A, Notes 1, 2				9.1	mΩ

Features

- Ultra-low On Resistance
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
  - easy to drive and to protect
- 175 °C Operating Temperature

Advantages

- Easy to mount
- Space savings
- High power density

Applications

- Automotive
  - Motor Drives
  - 42V Power Bus
  - ABS Systems
- DC/DC Converters and Off-line UPS
- Primary Switch for 24V and 48V Systems
- Distributed Power Architechtures and VRMs
- Electronic Valve Train Systems
- High Current Switching Applications
- High Voltage Synchronous Recifier

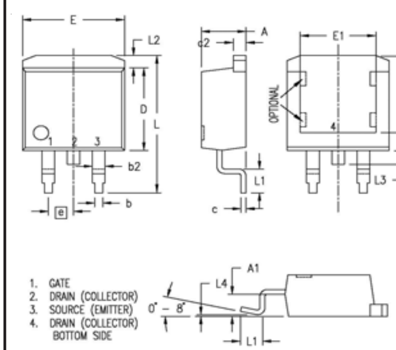
Symbol	Test Conditions	Characteristic Values			
(T_J = 25°C unless otherwise specified)		Min.	Typ.	Max.	
g_{fs}	V_{DS}= 10V, I_D = 60A, Note 1	55	93		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		5080		pF
C_{oss}			635		pF
C_{rss}			95		pF
$t_{d(on)}$	**Resistive Switching Times**		30		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 25A		47		ns
$t_{d(off)}$	R_G = 5Ω (External)		44		ns
t_f			28		ns
$Q_{g(on)}$	V_{GS}= 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 25A		104		nC
Q_{gs}			30		nC
Q_{gd}			29		nC
R_{thJC}				0.42	°C/W
R_{thCH}	TO-220		0.50		°C/W

Source-Drain Diode

Symbol	Test Conditions	Characteristic Values			
T_J = 25°C unless otherwise specified)		Min.	Typ.	Max.	
I_S	V_{GS} = 0V			130	A
I_{SM}	Pulse width limited by T_{JM}			350	A
V_{SD}	I_F = 25A, V_{GS} = 0V, Note 1			1.0	V
t_{rr}	I_F = 0.5 • I_S, -di/dt = 100A/μs		67		ns
I_{RM}	V_R = 0.5 • V_{DSS}, V_{GS} = 0V		4.7		A
Q_{rr}			160		nC

Notes: 1. Pulse test, t ≤ 300 μs; duty cycle, d ≤ 2%.
2. On through-hole packages, $R_{DS(on)}$ Kelvin test contact location must be 5 mm or less from the package body.

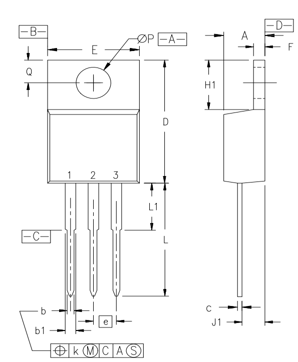
TO-263 (IXTA) Outline



Pins: 1 - Gate 2 - Drain
3 - Source 4, TAB - Drain

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.06	4.83	.160	.190
A1	2.03	2.79	.080	.110
b	0.51	0.99	.020	.039
b2	1.14	1.40	.045	.055
c	0.46	0.74	.018	.029
c2	1.14	1.40	.045	.055
D	8.64	9.65	.340	.380
D1	7.11	8.13	.280	.320
E	9.65	10.29	.380	.405
E1	6.86	8.13	.270	.320
e	2.54	BSC	.100	BSC
L	14.61	15.88	.575	.625
L1	2.29	2.79	.090	.110
L2	1.02	1.40	.040	.055
L3	1.27	1.78	.050	.070
L4	0	0.38	0	.015
R	0.46	0.74	.018	.029

TO-220 (IXTP) Outline



Pins: 1 - Gate 2 - Drain
3 - Source 4, TAB - Drain

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100 BSC		2.54 BSC	
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
ØP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

IXYS reserves the right to change limits, test conditions, and dimensions.

Fig. 1. Output Characteristics @ 25ºC

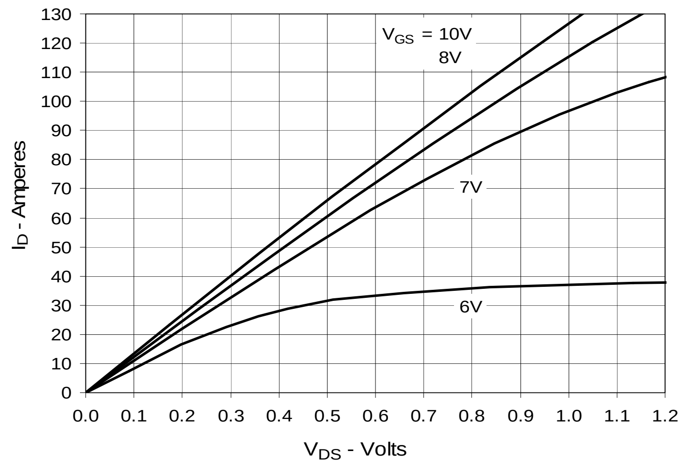


Fig. 2. Extended Output Characteristics @ 25ºC

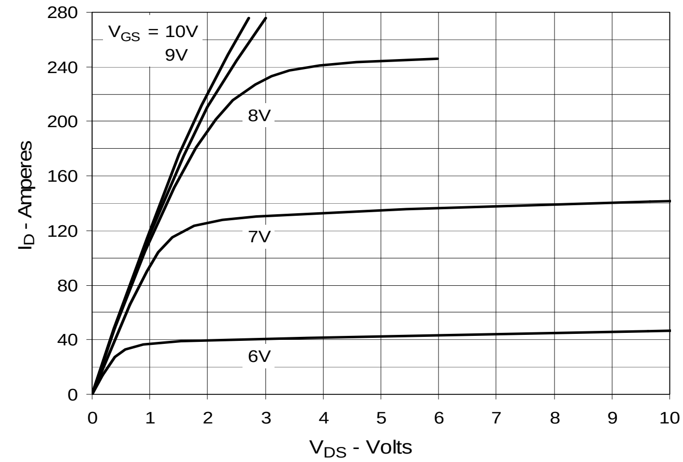


Fig. 3. Output Characteristics @ 150ºC

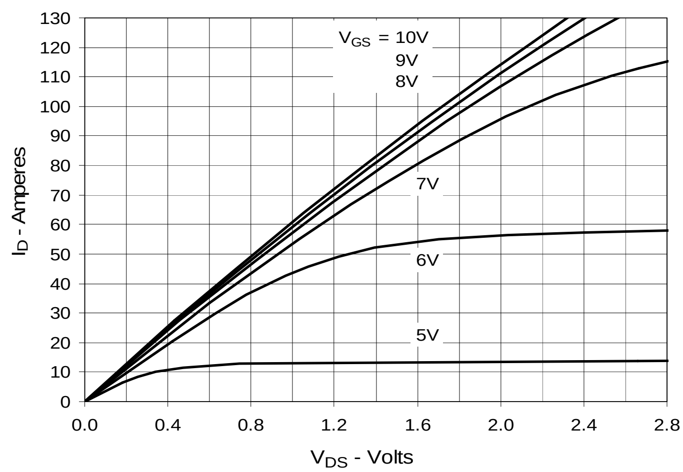


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 65A Value vs. Junction Temperature

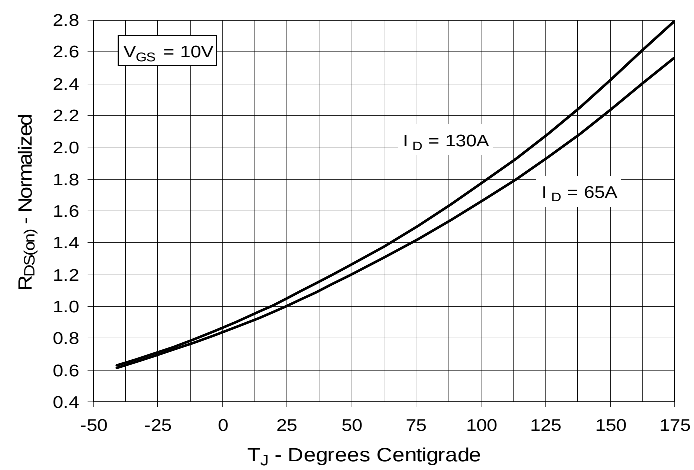


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 65A Value vs. Drain Current

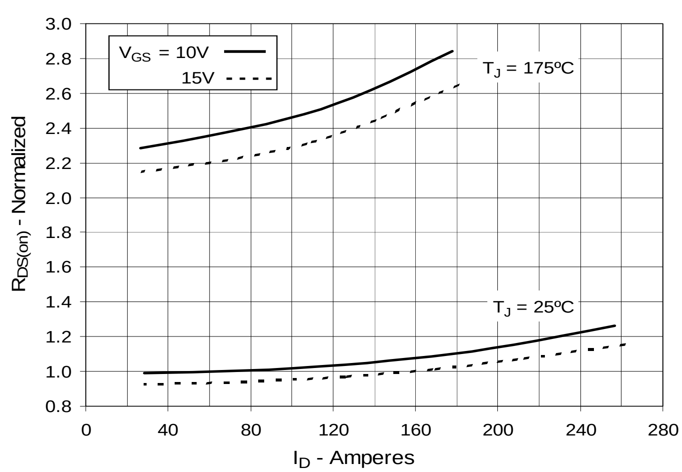


Fig. 6. Drain Current vs. Case Temperature

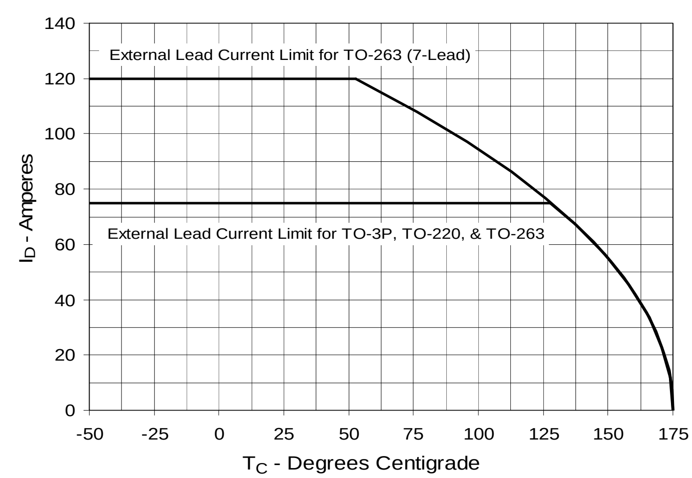


Fig. 7. Input Admittance

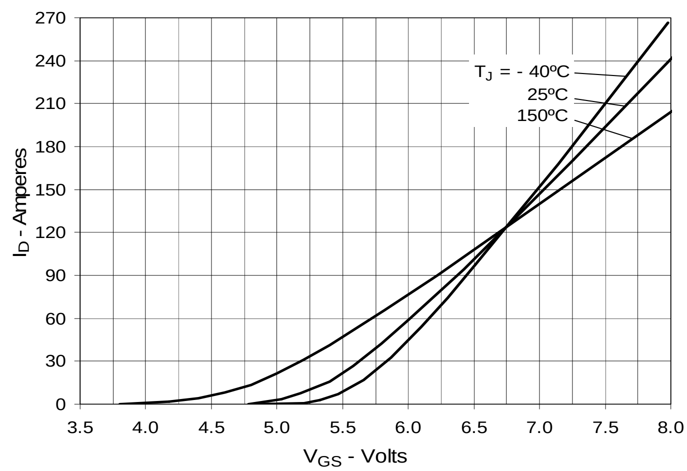


Fig. 8. Transconductance

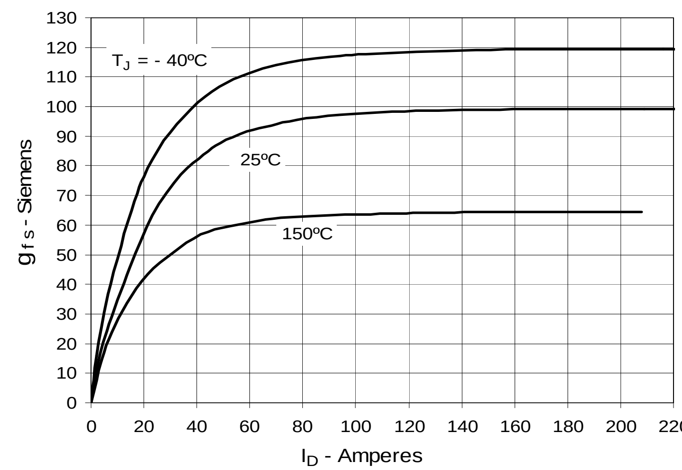


Fig. 9. Forward Voltage Drop of Intrinsic Diode

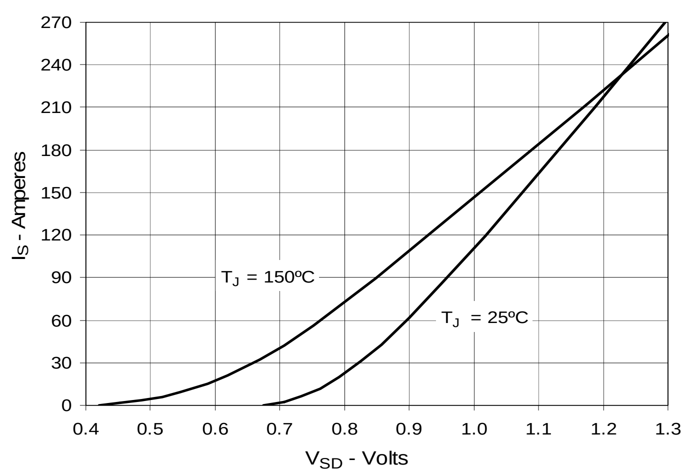


Fig. 10. Gate Charge

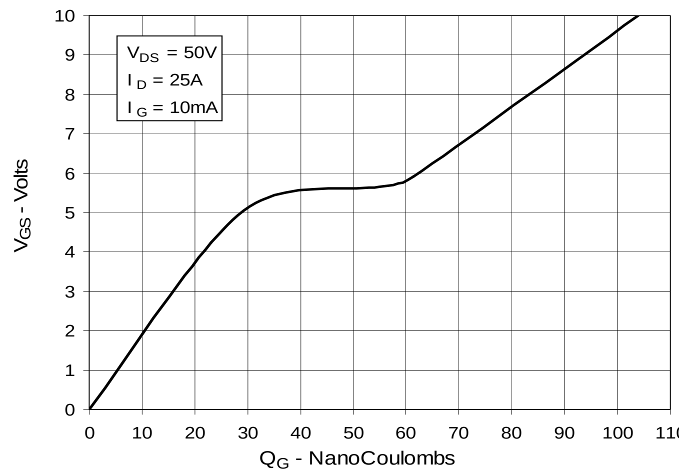


Fig. 11. Capacitance

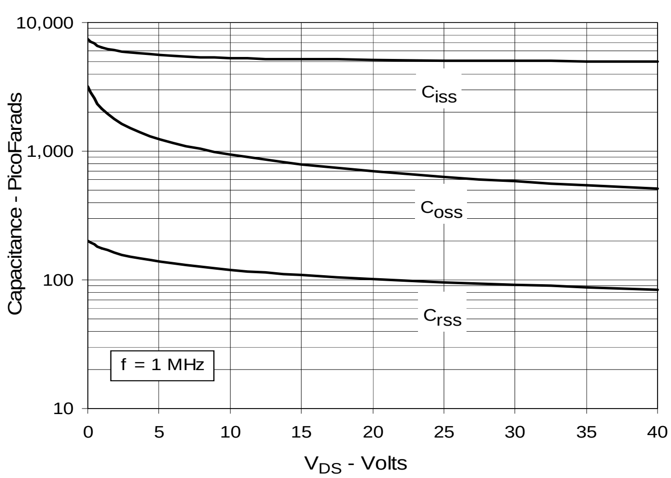


Fig. 12. Maximum Transient Thermal Impedance

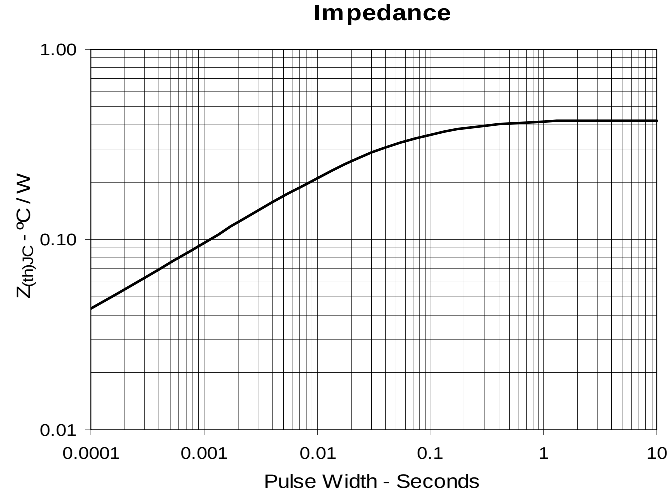


Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

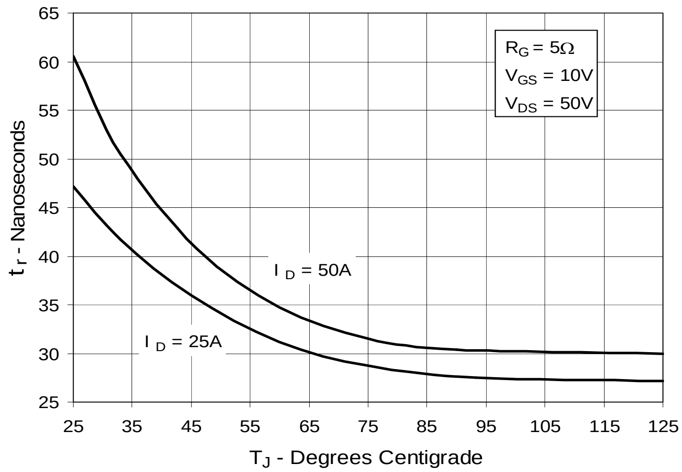


Fig. 14. Resistive Turn-on Rise Time vs. Drain Current

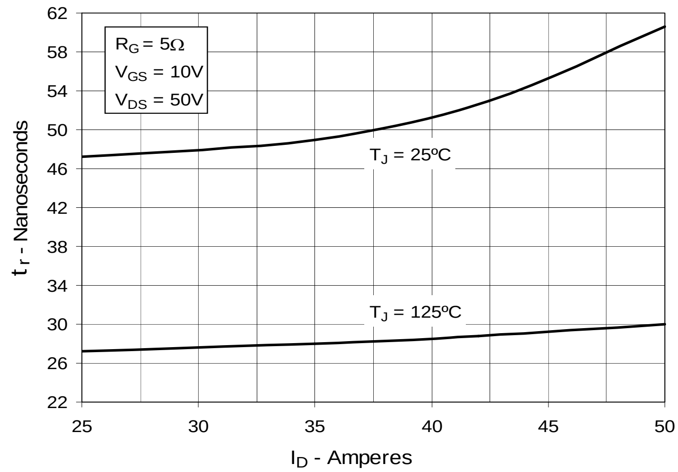


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

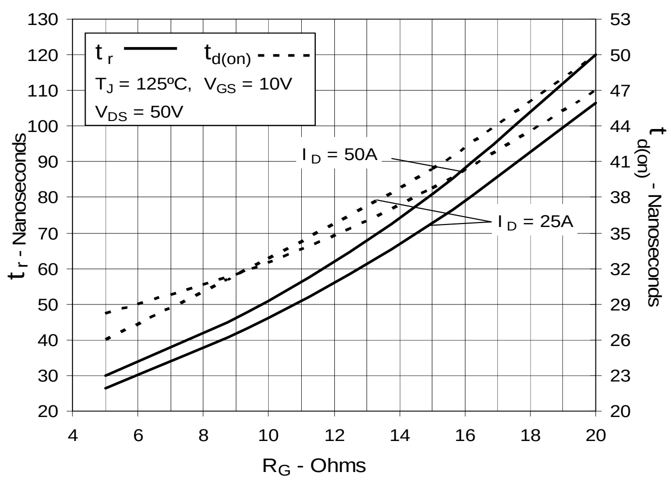


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

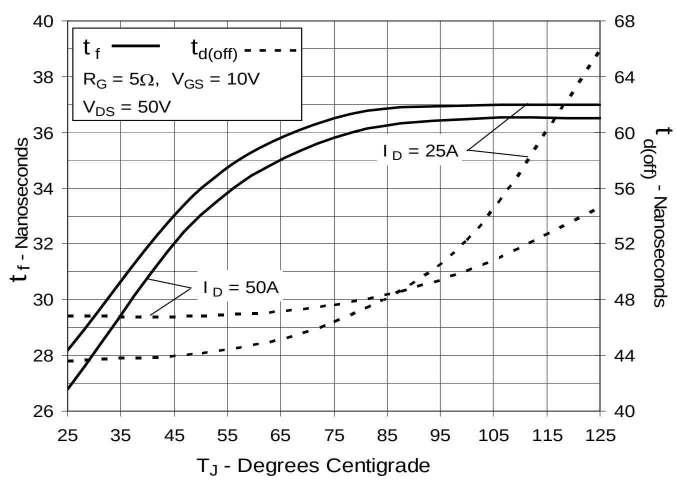


Fig. 17. Resistive Turn-off Switching Times vs. Drain Current

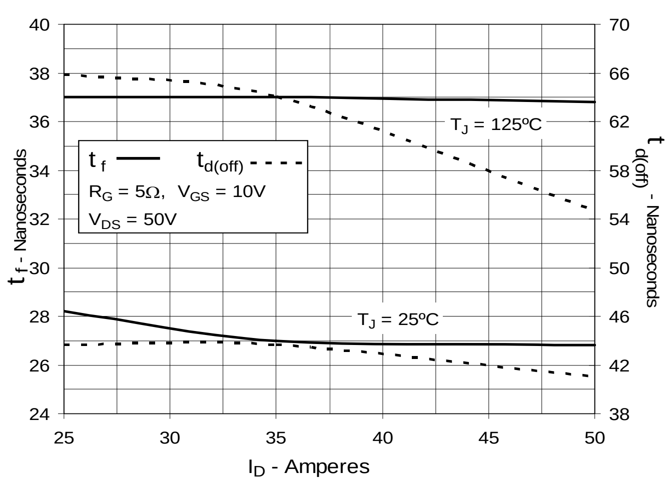


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance